



# PMEG045T150EIPD

45 V, 15 A low VF Trench MEGA Schottky barrier rectifier

27 September 2017

Product data sheet

## 1. General description

Trench Maximum Efficiency General Application (MEGA) Schottky barrier rectifier encapsulated in a CFP15 (SOT1289) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 15$  A
- Reverse voltage:  $V_R \leq 45$  V
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- High power capability due to clip-bonding technology and heat sink
- Small and thin SMD plastic package, typical height 0.78 mm
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Freewheeling application
- Reverse polarity protection
- Low power consumption application

## 4. Quick reference data

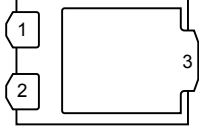
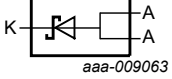
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_R$	reverse voltage	$T_j = 25$ °C		-	-	45	V
$V_F$	forward voltage	$I_F = 15$ A; $T_j = 25$ °C; pulsed	[1]	-	510	570	mV
$I_R$	reverse current	$V_R = 10$ V; $T_j = 25$ °C; pulsed	[1]	-	14	51	$\mu$ A
		$V_R = 45$ V; $T_j = 25$ °C; pulsed	[1]	-	30	98	$\mu$ A

[1] Very short pulse, in order to maintain a stable junction temperature.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 <p>CFP15 (SOT1289)</p>	
2	A	anode		
3	K	cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG045T150EIPD	CFP15	plastic, thermal enhanced ultra thin SMD package; 3 terminals; 5.8 x 4.3 x 0.78 mm body	SOT1289

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG045T150EIPD	045T M15E

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	45	V
$I_F$	forward current	$T_{sp} \leq 118\text{ °C}; \delta = 1$		-	21	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}; T_{j(\text{init})} = 25\text{ °C};$ square wave		-	130	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	-	1.66	W
			[2]	-	2.15	W
$T_j$	junction temperature			-	175	°C
$T_{amb}$	ambient temperature			-55	175	°C
$T_{stg}$	storage temperature			-65	175	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	3	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[4] Soldering point of cathode tab.

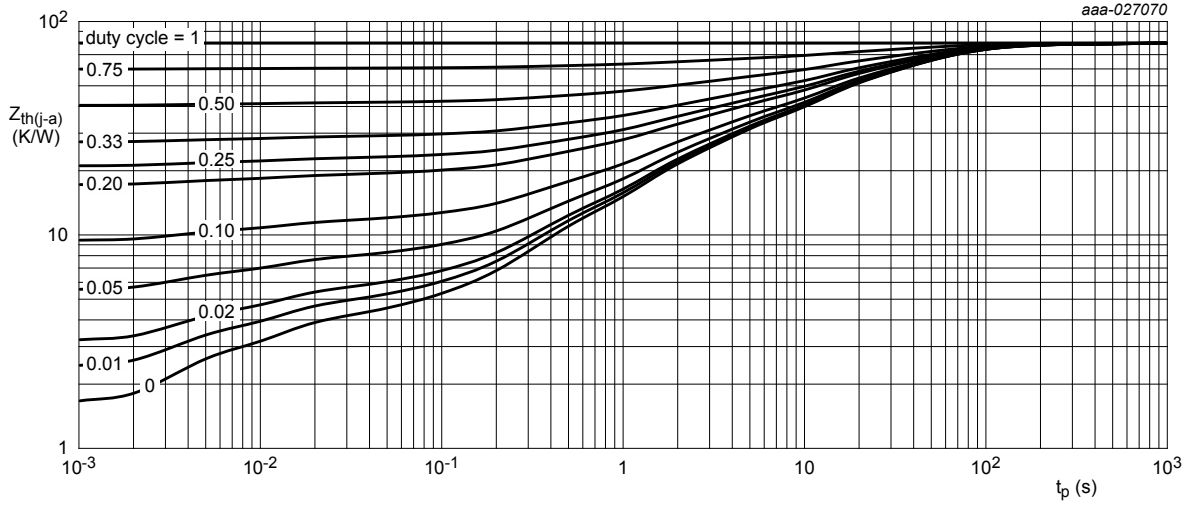


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

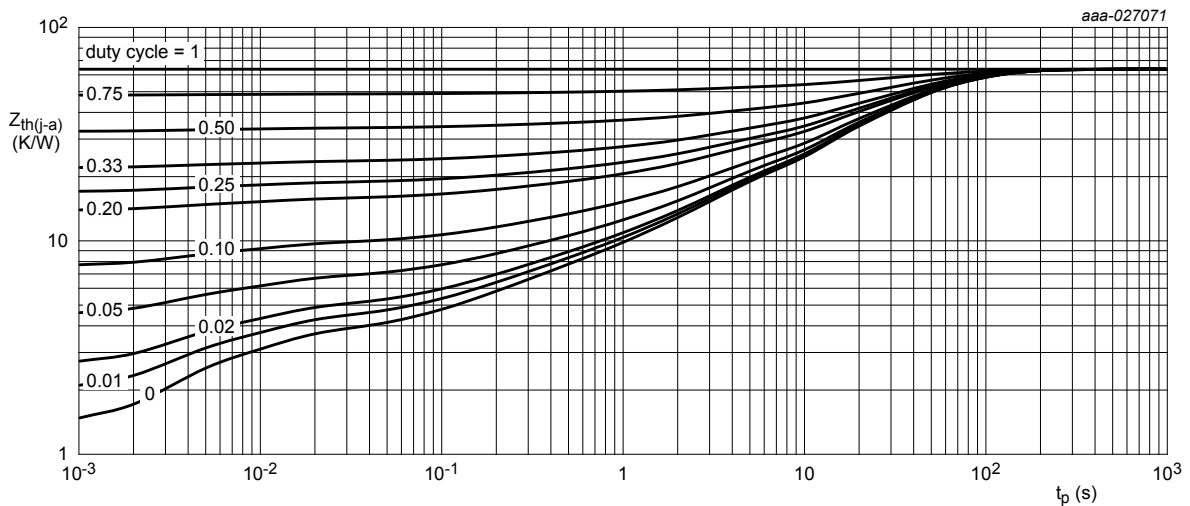


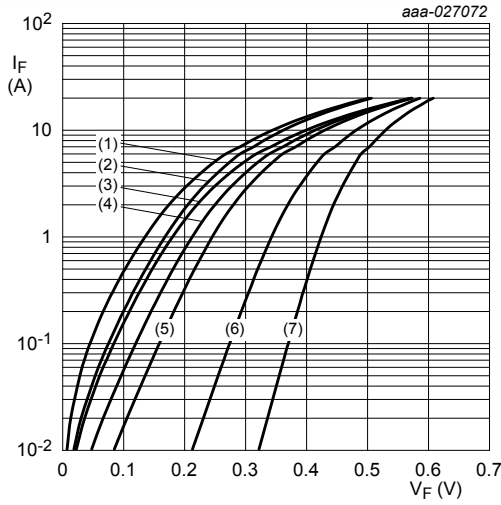
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

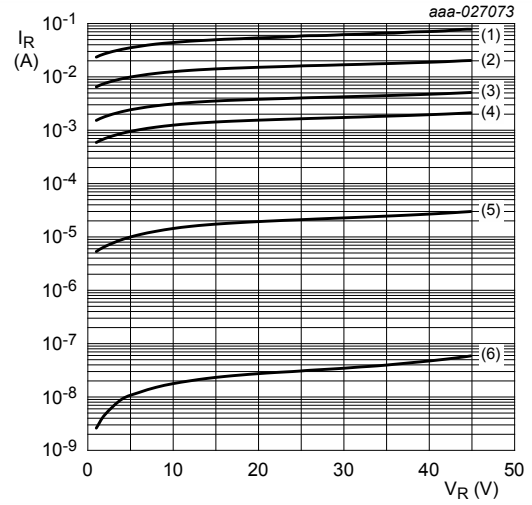
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	45	-	-	V
$V_F$	forward voltage	$I_F = 1 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	335	375	mV
		$I_F = 5 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	410	460	mV
		$I_F = 10 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	465	520	mV
		$I_F = 15 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	510	570	mV
		$I_F = 15 \text{ A}$ ; $T_j = -40 \text{ °C}$ ; pulsed	[1]	-	550	-	mV
		$I_F = 15 \text{ A}$ ; $T_j = 125 \text{ °C}$ ; pulsed	[1]	-	465	-	mV
$I_R$	reverse current	$V_R = 10 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	14	51	$\mu\text{A}$
		$V_R = 30 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	23	-	$\mu\text{A}$
		$V_R = 45 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; pulsed	[1]	-	30	98	$\mu\text{A}$
		$V_R = 45 \text{ V}$ ; $T_j = 125 \text{ °C}$ ; pulsed	[1]	-	20	-	mA
$C_d$	diode capacitance	$V_R = 1 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ °C}$		-	1.7	-	nF
		$V_R = 10 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_j = 25 \text{ °C}$		-	0.72	-	nF
$t_{rr}$	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$ ; $I_R = 0.5 \text{ A}$ ; $I_{R(\text{meas})} = 0.1 \text{ A}$ ; $T_j = 25 \text{ °C}$		-	49	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A}/\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; $I_F = 6 \text{ A}$ ; $V_R = 26 \text{ V}$		-	21	-	ns

[1] Very short pulse, in order to maintain a stable junction temperature.



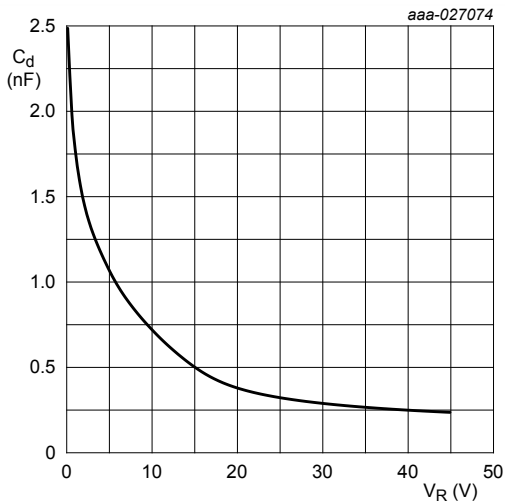
pulsed condition  
 (1)  $T_j = 175\text{ }^\circ\text{C}$   
 (2)  $T_j = 150\text{ }^\circ\text{C}$   
 (3)  $T_j = 125\text{ }^\circ\text{C}$   
 (4)  $T_j = 100\text{ }^\circ\text{C}$   
 (5)  $T_j = 85\text{ }^\circ\text{C}$   
 (6)  $T_j = 25\text{ }^\circ\text{C}$   
 (7)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 3. Forward current as a function of forward voltage; typical values**



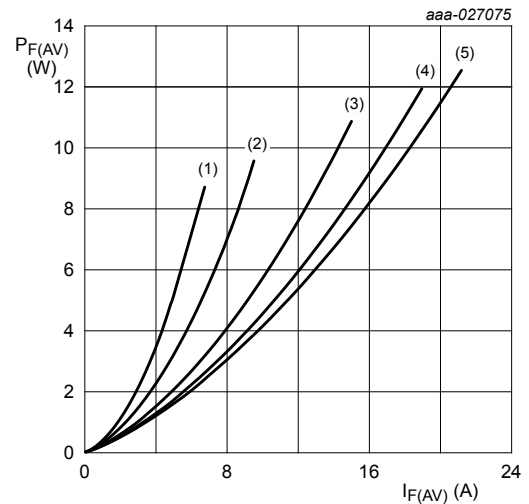
pulsed condition  
 (1)  $T_j = 150\text{ }^\circ\text{C}$   
 (2)  $T_j = 125\text{ }^\circ\text{C}$   
 (3)  $T_j = 100\text{ }^\circ\text{C}$   
 (4)  $T_j = 85\text{ }^\circ\text{C}$   
 (5)  $T_j = 25\text{ }^\circ\text{C}$   
 (6)  $T_j = -40\text{ }^\circ\text{C}$

**Fig. 4. Reverse current as a function of reverse voltage; typical values**



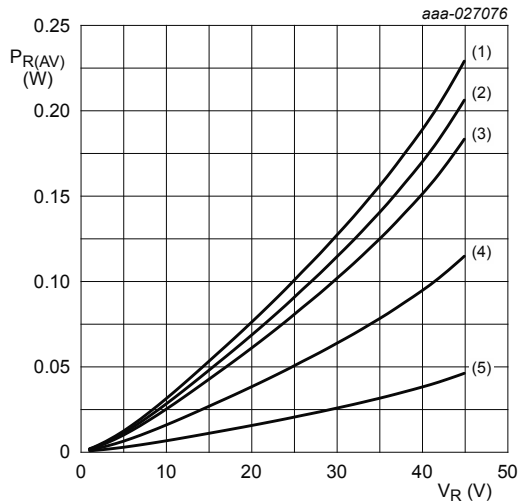
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

**Fig. 5. Diode capacitance as a function of reverse voltage; typical values**



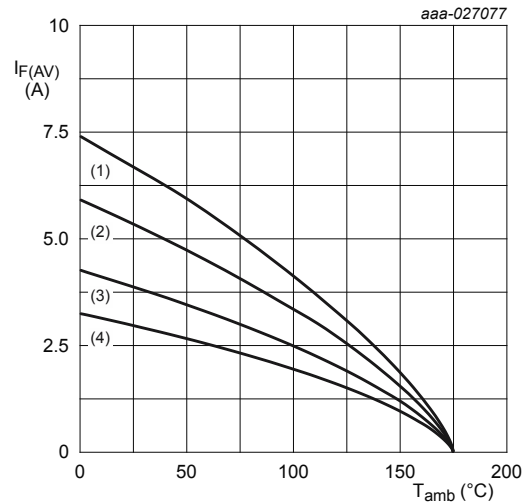
$T_j = 100\text{ }^\circ\text{C}$   
 (1)  $\delta = 0.1$   
 (2)  $\delta = 0.2$   
 (3)  $\delta = 0.5$   
 (4)  $\delta = 0.8$   
 (5)  $\delta = 1$ ; DC

**Fig. 6. Average forward power dissipation as a function of average forward current; typical values**



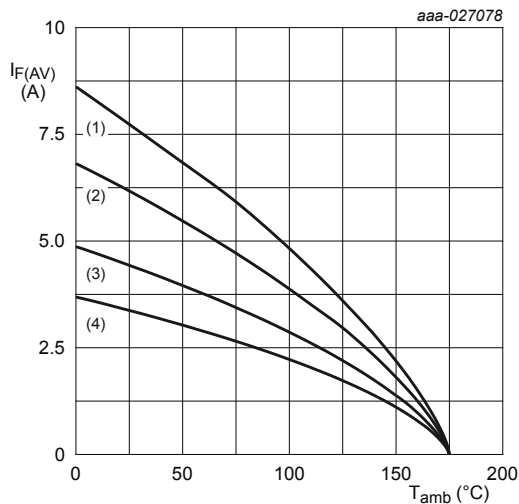
$T_j = 100\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.9$   
 (3)  $\delta = 0.8$   
 (4)  $\delta = 0.5$   
 (5)  $\delta = 0.2$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



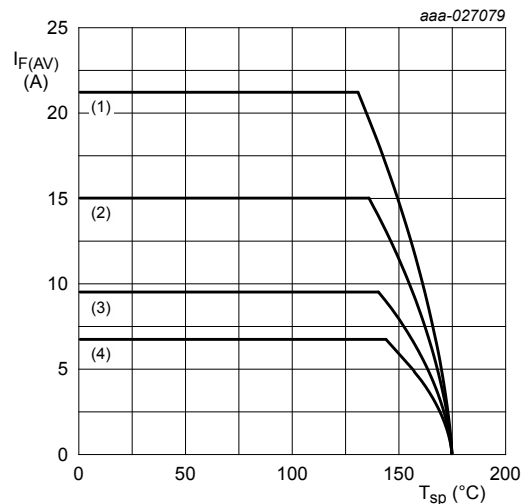
FR4 PCB, standard footprint  
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 175\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 9. Average forward current as a function of ambient temperature; typical values



$T_j = 175\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of solder point temperature; typical values

### 11. Test information

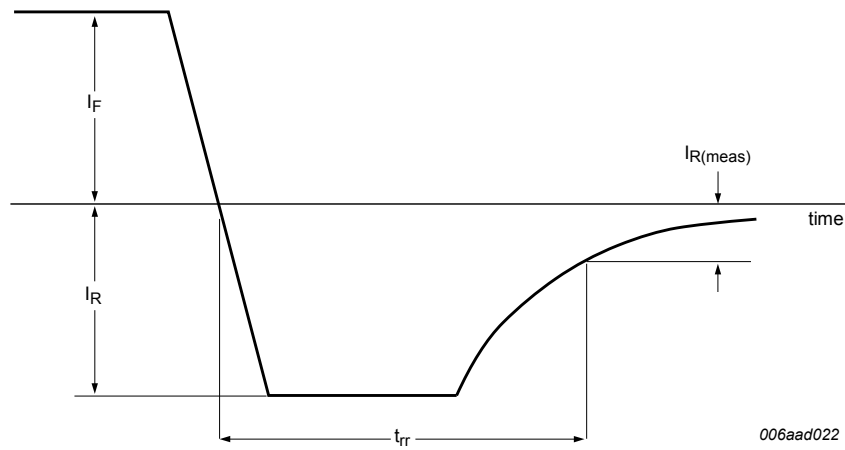


Fig. 11. Reverse recovery definition; step recovery

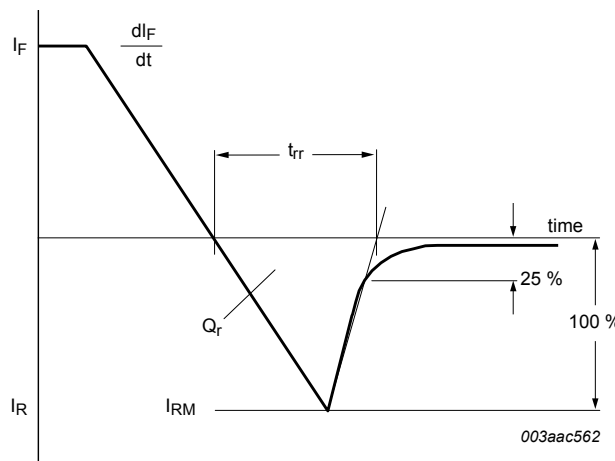


Fig. 12. Reverse recovery definition; ramp recovery

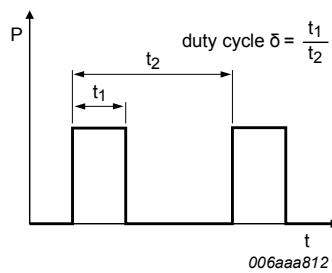


Fig. 13. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC, and } I_{RMS} = I_M \times \sqrt{\delta}$$

with  $I_{RMS}$  defined as RMS current.



Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

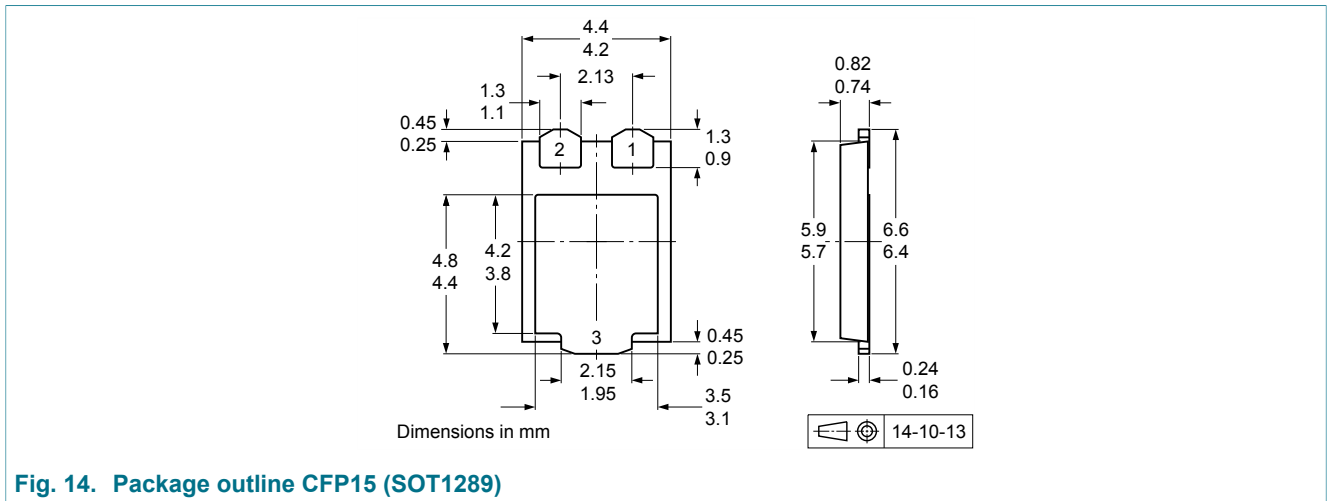


Fig. 14. Package outline CFP15 (SOT1289)

13. Soldering

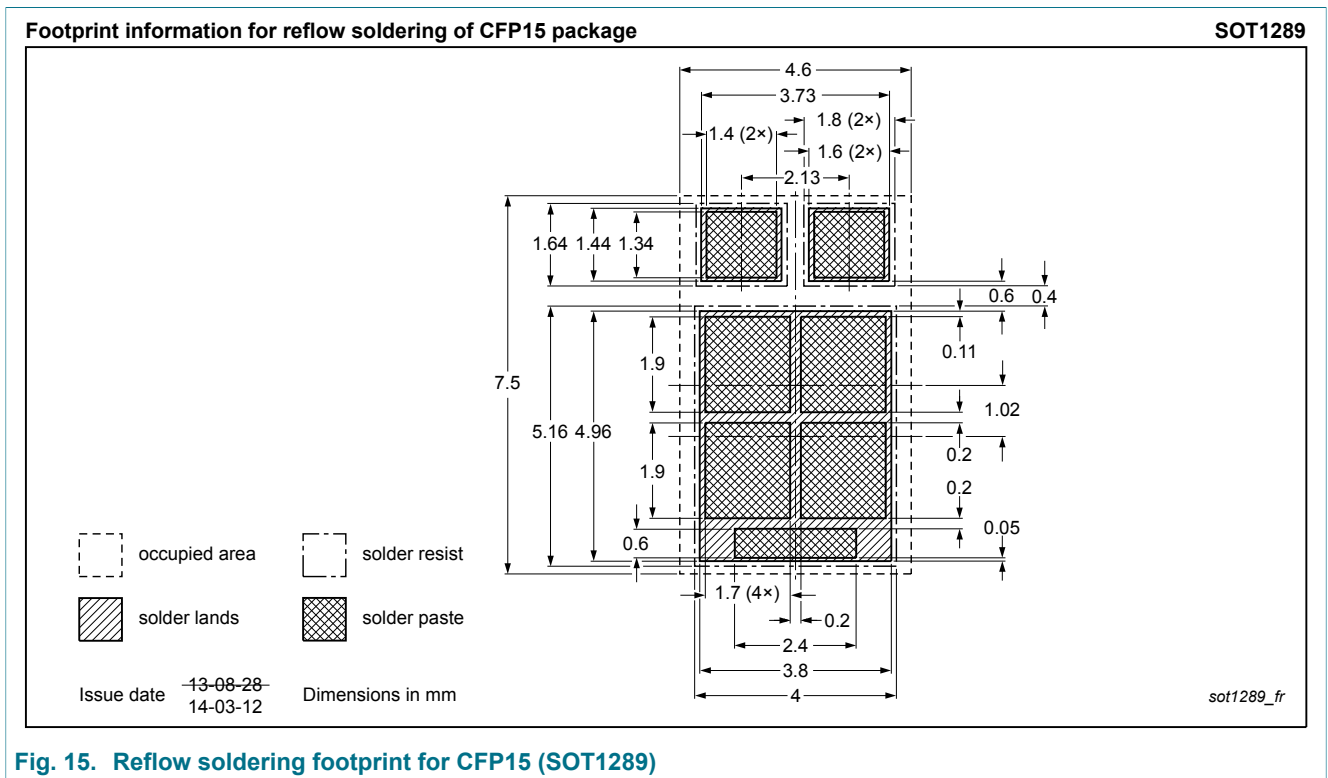


Fig. 15. Reflow soldering footprint for CFP15 (SOT1289)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG045T150EIPD v.1	20170927	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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